

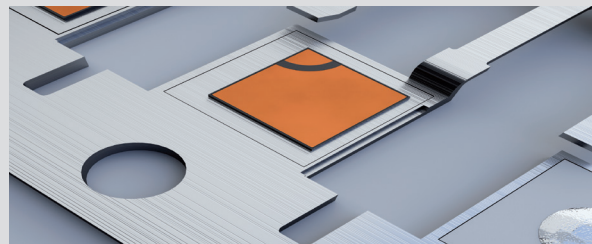
## New Product: Microbond® DA5118 D Solvent Clean High Lead Dispensing Solder Paste

DA5118 D is Solvent Clean High Lead Solder Paste designed for use in die, clip and bridge applications. Its stable rheology provides exceptional dispensing performance suitable for high volume production and high density leadframe applications. The paste exhibits long work life, low void rates and easy cleanability.

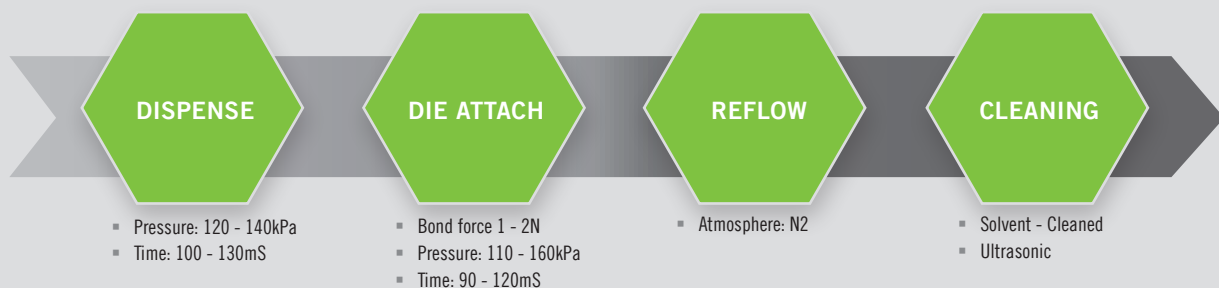


### DA5118 D Benefits

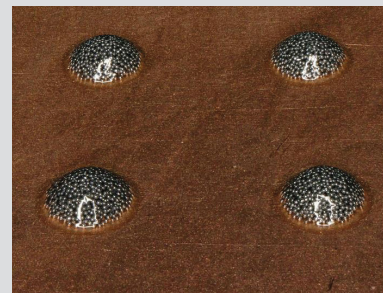
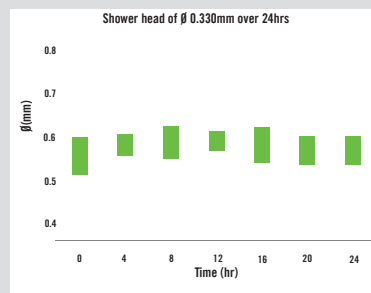
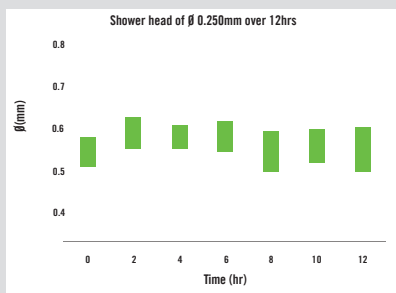
- Halogen zero
- Stable rheology
- Exceptional dispensing consistency
- Wide reflow temperature window
- Low void rates
- Easy cleanability
- Long work life
- Long pot life



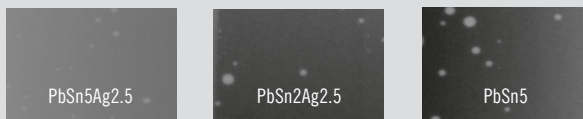
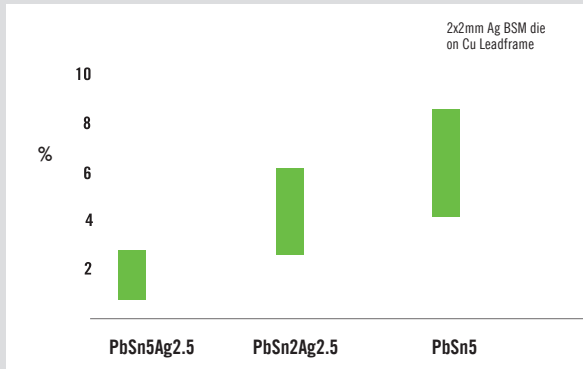
### DA5118 D Solder Paste Process and Application



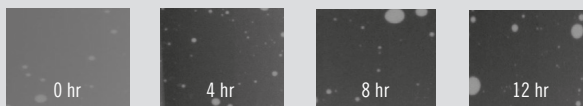
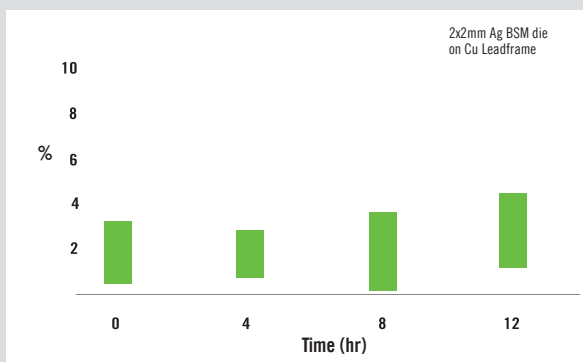
### Continuous Dispensing Performance



### Voids Performance - Alloy



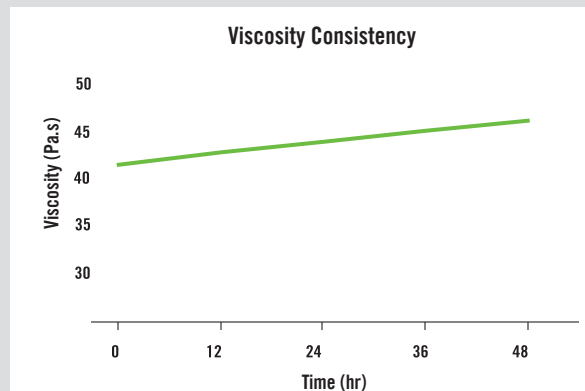
### Voids Performance - Over Time



### Product Properties Table

Physical Properties	DA5118 D
Alloy	PbSn2Ag2.5 (Type 3)
	PbSn5Ag2.5 (Type 3)
	PbSn5 (Type 4)
Metal Content	87%
Halogen Content	Halogen-zero
Flux Activity	ROLO
Application/Process	
Dispensing (min Dia)	Yes (Ø 0.25mm)
Reflow Temperature	360 - 390°C
Reflow Atmosphere	N2
Features & Benefits	
Cleaning	Solvent Clean
Work Life	12 hr
Shelf Life	6 mths
Storage Condition	2 - 10°C -10 - 5°C (PbSn2Ag2.5)

### Viscosity Performance



The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application. The Heraeus logo, Heraeus, Microbond® and the Microbond figurative mark are trademarks or registered trademarks of Heraeus Holding GmbH or its affiliates. All rights reserved